

**AMENDMENTS TO THE SPECIFICATION:**

Please amend the specification as follows:

Please replace the last paragraph starting on page 9, at line 17 with the following:

In operation, exposure apparatus 21 transfers a pattern of an integrated circuit from a reticle 80 onto semiconductor wafer 68. Exposure apparatus 21 can be mounted to a base the ground 82, i.e. ~~the ground~~ or via a vibration isolation system (not shown). An apparatus frame 72 is rigid and supports the components of exposure apparatus 21, including a reticle stage 76, wafer stage 66, lens assembly 78, and an illumination system 74.

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